

LEADED

# BGA SOLDER PASTE



Sn63/Pb37

Melting point 183°C



## Product Usage

● ● ●  
TIN PASTE

Type number	BST-503-JP
Types of	Solder Paste
Composition	Sn63/Pb37
Melting point	183°C
G.W.	70g
size	1.41*1.28 in



Sn63/Pb37

Melting point at medium temperature

183°C





Low residue



Solder spot bright



Rapid welding

# Welding requirements for a wide range of products



**SMT  
patch**



**LED  
patch**



**BGA  
welding**



# Product List

G.W.:70g

